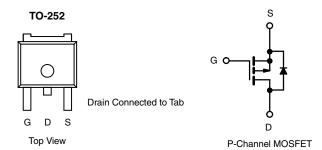


# Automotive P-Channel 80 V (D-S) 175 °C MOSFET

| PRODUCT SUMMARY                           |        |  |  |  |
|---|--------|--|--|--|
| V <sub>DS</sub> (V)                       | - 80   |  |  |  |
| $R_{DS(on)}(\Omega)$ at $V_{GS}$ = - 10 V | 0.028  |  |  |  |
| I <sub>D</sub> (A)                        | - 48   |  |  |  |
| Configuration                             | Single |  |  |  |



### **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- AEC-Q101 Qualifiedd
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



| ORDERING INFORMATION            |                 |
|---------------------------------|-----------------|
| Package                         | TO-252          |
| Lead (Pb)-free and Halogen-free | SQD50P08-28-GE3 |

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted) |                         |                                   |               |    |  |
|---|-------------------------|-----------------------------------|---------------|----|--|
| PARAMETER   | SYMBOL                  | LIMIT                             | UNIT          |    |  |
| Drain-Source Voltage  |                         | $V_{DS}$                          | - 80          | V  |  |
| Gate-Source Voltage   |                         | $V_{GS}$                          | ± 20          |    |  |
| Continuous Drain Current  | T <sub>C</sub> = 25 °C  | l <sub>D</sub>                    | - 48          |    |  |
|   | T <sub>C</sub> = 125 °C |                                   | - 28          |    |  |
| Continuous Source Current (Diode Conduction) <sup>a</sup>                 |                         | I <sub>S</sub>                    | - 50          | Α  |  |
| Pulsed Drain Current <sup>b</sup>   |                         | I <sub>DM</sub>                   | - 190         |    |  |
| Single Pulse Avalanche Current  | L = 0.1 mH              | I <sub>AS</sub>                   | - 45          |    |  |
| Single Pulse Avalanche Energy   | L = 0.1 mm              | E <sub>AS</sub>                   | 100           | mJ |  |
| Maximum Power Dissipation <sup>b</sup>                                    | T <sub>C</sub> = 25 °C  | D                                 | 136           | W  |  |
|   | T <sub>C</sub> = 125 °C | $P_D$                             | 45            | VV |  |
| Operating Junction and Storage Temperature Range                          |                         | T <sub>J</sub> , T <sub>stg</sub> | - 55 to + 175 | °C |  |

| THERMAL RESISTANCE RATINGS |                        |                   |       |       |  |
|----------------------------|------------------------|-------------------|-------|-------|--|
| PARAMETER                  |                        | SYMBOL            | LIMIT | UNIT  |  |
| Junction-to-Ambient        | PCB Mount <sup>c</sup> | $R_{thJA}$        | 50    | °C/W  |  |
| Junction-to-Case (Drain)   |                        | R <sub>thJC</sub> | 1.1   | G/ VV |  |

### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



| PARAMETER                                     | SYMBOL                   | TEST CONDITIONS   |   | MIN.  | TYP.   | MAX.  | UNIT |
|---|--------------------------|---|---|-------|--------|-------|------|
| Static  |                          |   |   |       |        |       |      |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>          | V <sub>GS</sub> = 0, I <sub>D</sub> = - 250 μA  |   | - 80  | -      | -     | V    |
| Gate-Source Threshold Voltage                 | V <sub>GS(th)</sub>      | V <sub>DS</sub> =   | V <sub>GS</sub> , I <sub>D</sub> = - 250 μA         | - 2.5 | - 3.0  | - 3.5 | V    |
| Gate-Source Leakage                           | I <sub>GSS</sub>         | V <sub>DS</sub> =   | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$   |       | -      | ± 100 | nA   |
|   |                          | V <sub>GS</sub> = 0 V   | V <sub>DS</sub> = - 80 V                            | -     | -      | - 1   |      |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>         | V <sub>GS</sub> = 0 V   | V <sub>DS</sub> = - 80 V, T <sub>J</sub> = 125 °C   | -     | -      | - 50  | μΑ   |
|   |                          | V <sub>GS</sub> = 0 V   | V <sub>DS</sub> = - 80 V, T <sub>J</sub> = 175 °C   | -     | -      | - 250 |      |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>       | V <sub>GS</sub> = - 10 V  | $V_{DS} \le -5 \text{ V}$                           | - 50  | -      | -     | Α    |
| Drain-Source On-State Resistance <sup>a</sup> |                          | V <sub>GS</sub> = - 10 V  | I <sub>D</sub> = - 12.5 A                           | -     | 0.023  | 0.028 | Ω    |
|   | R <sub>DS(on)</sub>      | V <sub>GS</sub> = - 10 V  | I <sub>D</sub> = - 12.5 A, T <sub>J</sub> = 125 °C  | -     | -      | 0.049 |      |
|   |                          | V <sub>GS</sub> = - 10 V  | I <sub>D</sub> = - 12.5 A, T <sub>J</sub> = 175 °C  | -     | -      | 0.061 |      |
| Forward Transconductance <sup>b</sup>         | 9 <sub>fs</sub>          | V <sub>DS</sub> = -   | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 12.5 A |       | 32     | -     | S    |
| Dynamic <sup>b</sup>                          |                          |   |   |       |        |       |      |
| Input Capacitance                             | C <sub>iss</sub>         |   |   | -     | 4826   | 6035  |      |
| Output Capacitance                            | C <sub>oss</sub>         | $V_{GS} = 0 V$  | V <sub>DS</sub> = - 25 V, f = 1 MHz                 | -     | 343    | 430   | pF   |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>         |   |   | -     | 224    | 280   |      |
| Total Gate Charge <sup>c</sup>                | Qg                       |   |   | -     | 95     | 145   |      |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>          | V <sub>GS</sub> = - 10 V  | $V_{DS} = -40 \text{ V}, I_{D} = -12.5 \text{ A}$   | -     | 19     | -     | nC   |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>          |   |   | -     | 26     | -     |      |
| Gate Resistance                               | R <sub>g</sub>           | f = 1 MHz   |   | 1.73  | 3.47   | 5.21  | Ω    |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>       |   |   | -     | 15     | 23    |      |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>           | $V_{DD} = -40 \text{ V}, R_L = 3.8 \Omega$ $I_D \cong -10.5 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$ |   | -     | 11     | 17    | ns   |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>      |   |   | -     | 65     | 98    |      |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>           |   |   | -     | 16     | 24    |      |
| Source-Drain Diode Ratings and Chara          | acteristics <sup>b</sup> |   |   |       |        |       |      |
| Pulsed Current <sup>a</sup>                   | I <sub>SM</sub>          |   |   | -     | -      | - 190 | Α    |
| Forward Voltage                               | $V_{SD}$                 | $I_F = -10 \text{ A}, V_{GS} = 0$   |   | -     | - 0.82 | - 1.5 | V    |

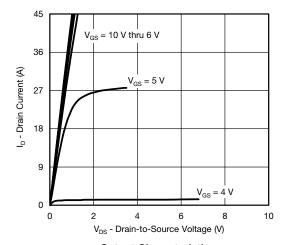
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

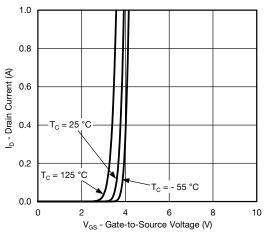
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



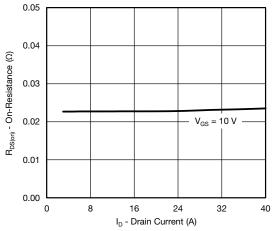
## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



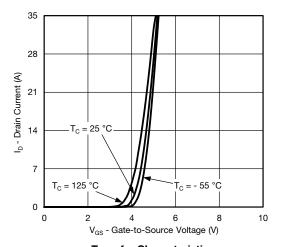
### **Output Characteristics**



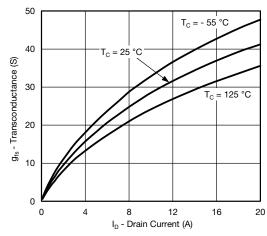
**Transfer Characteristics** 



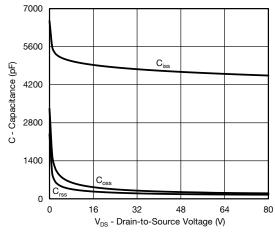
On-Resistance vs. Drain Current



**Transfer Characteristics** 



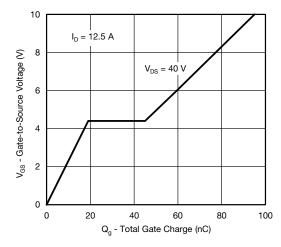
Transconductance



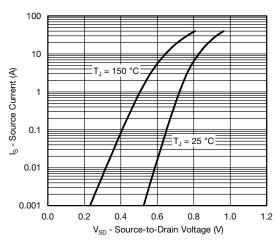
Capacitance



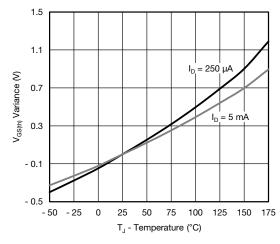
### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



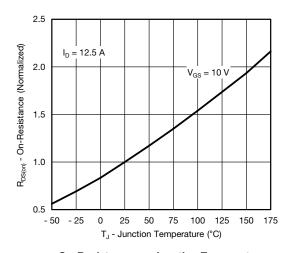
**Gate Charge** 



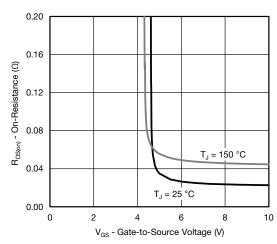
**Source Drain Diode Forward Voltage** 



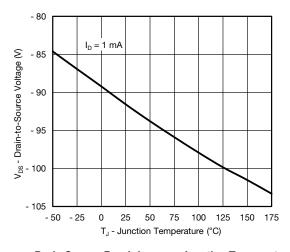
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



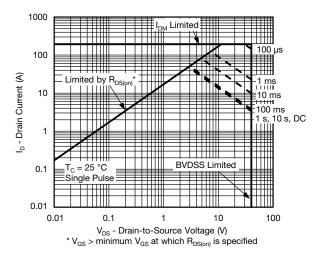
On-Resistance vs. Gate-to-Source Voltage



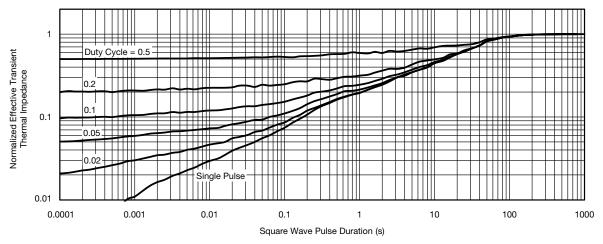
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_A = 25 \, ^{\circ}C$ , unless otherwise noted)



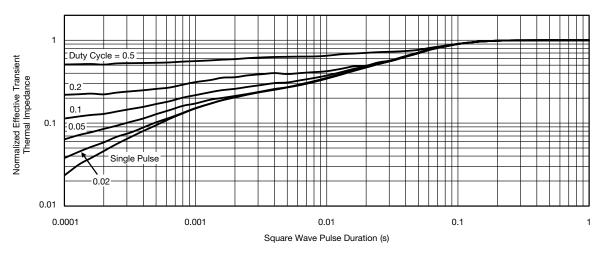
### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

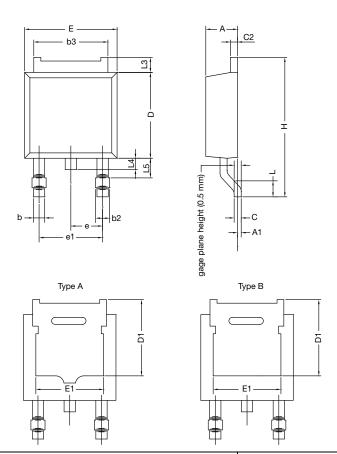
#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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## **TO-252AA Case Outline**



| DIM. | MILLIM   | METERS | INCHES    |       |  |
|------|----------|--------|-----------|-------|--|
|      | MIN.     | MAX.   | MIN.      | MAX.  |  |
| Α    | 2.18     | 2.38   | 0.086     | 0.094 |  |
| A1   | -        | 0.127  | -         | 0.005 |  |
| b    | 0.64     | 0.88   | 0.025     | 0.035 |  |
| b2   | 0.76     | 1.14   | 0.030     | 0.045 |  |
| b3   | 4.95     | 5.46   | 0.195     | 0.215 |  |
| С    | 0.46     | 0.61   | 0.018     | 0.024 |  |
| C2   | 0.46     | 0.89   | 0.018     | 0.035 |  |
| D    | 5.97     | 6.22   | 0.235     | 0.245 |  |
| D1   | 4.10     | -      | 0.161     | -     |  |
| E    | 6.35     | 6.73   | 0.250     | 0.265 |  |
| E1   | 4.32     | -      | 0.170     | =     |  |
| Н    | 9.40     | 10.41  | 0.370     | 0.410 |  |
| е    | 2.28 BSC |        | 0.090     | BSC   |  |
| e1   | 4.56 BSC |        | 0.180 BSC |       |  |
| L    | 1.40     | 1.78   | 0.055     | 0.070 |  |
| L3   | 0.89     | 1.27   | 0.035     | 0.050 |  |
| L4   | -        | 1.02   | -         | 0.040 |  |
| L5   | 1.01     | 1.52   | 0.040     | 0.060 |  |

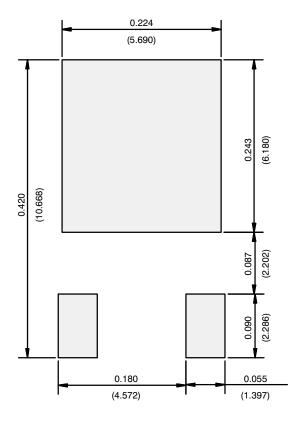
# ECN: T24-0298-Rev. B, 29-Jul-2024 DWG: 6019

#### Notes

- Dimension L3 is for reference only
- Dimension D1 and E1 on type A and B is the same



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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